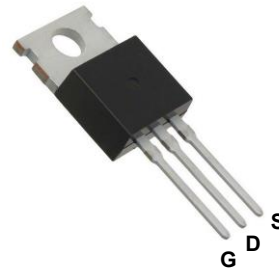
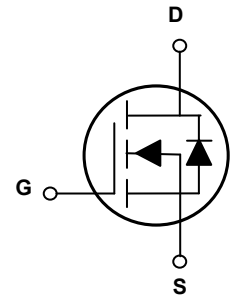


**Main Product Characteristics**

$V_{DS}$	60V
$R_{DS(ON)}$	1.8mΩ
$I_D$	200A



TO-220



Schematic Diagram

**Features and Benefits**

- Advanced MOSFET process technology
- Ideal for high efficiency switched mode power supplies
- Low on-resistance with low gate charge
- Fast switching and reverse body recovery



**Description**

The GSGH06200 utilizes the latest techniques to achieve high cell density and low on-resistance. These features make this device extremely efficient and reliable for use in high efficiency switch mode power supply and a wide variety of other applications.

**Absolute Maximum Ratings** ( $T_c=25^{\circ}C$  unless otherwise specified)

Parameter	Symbol	Max.	Unit
Drain-Source Voltage	$V_{DS}$	60	V
Gate-Source Voltage	$V_{GS}$	±20	V
Drain Current-Continuous	$I_D$	200	A
Drain Current-Continuous ( $T_c=100^{\circ}C$ )		150	
Drain Current-Pulsed	$I_{DM}$	800	A
Maximum Power Dissipation	$P_D$	255	W
Derating Factor	$P_D$	1.7	W/°C
Single Pulse Avalanche Energy <sup>5</sup>	$E_{AS}$	2000	mJ
Thermal Resistance, Junction-to-Case <sup>2</sup>	$R_{\theta JC}$	0.59	°C/W
Operating Junction Temperature Range	$T_J$	-55 To +175	°C
Storage Temperature Range	$T_{STG}$	-55 To +175	°C

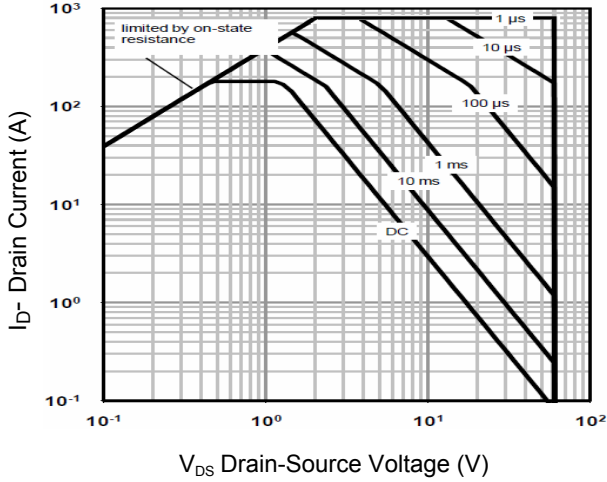
**Electrical Characteristics** ( $T_C=25^\circ\text{C}$  unless otherwise specified)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
<b>On/Off Characteristics</b>						
Drain-Source Breakdown Voltage	$BV_{DSS}$	$V_{GS}=0V, I_D=250\mu A$	60	-	-	V
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS}=60V, V_{GS}=0V$	-	-	1	$\mu A$
Gate-Body Leakage Current	$I_{GSS}$	$V_{GS}=\pm 20V, V_{DS}=0V$	-	-	$\pm 100$	nA
Gate Threshold Voltage <sup>3</sup>	$V_{GS(th)}$	$V_{GS}=V_{DS}, I_D=250\mu A$	2.2	2.7	3.5	V
Static Drain-Source On-Resistance <sup>3</sup>	$R_{DS(on)}$	$V_{GS}=10V, I_D=100A$	-	1.8	2.2	m $\Omega$
Forward Transconductance <sup>3</sup>	$g_{fs}$	$V_{DS}=10V, I_D=100A$	-	60	-	S
<b>Dynamic and Switching Characteristics</b>						
Input Capacitance <sup>4</sup>	$C_{iss}$	$V_{DS}=30V, V_{GS}=0V, F=1MHz$	-	9200	-	pF
Output Capacitance <sup>4</sup>	$C_{oss}$		-	1900	-	
Reverse Transfer Capacitance <sup>4</sup>	$C_{rss}$		-	61	-	
Turn-On Delay Time <sup>4</sup>	$t_{d(on)}$	$V_{DD}=30V, R_G=4.7\Omega, V_{GS}=10V, I_D=100A$	-	23	-	nS
Rise Time <sup>4</sup>	$t_r$		-	19	-	
Turn-Off Delay Time <sup>4</sup>	$t_{d(off)}$		-	58	-	
Fall Time <sup>4</sup>	$t_f$		-	14	-	
Total Gate Charge <sup>4</sup>	$Q_g$	$V_{DS}=30V, I_D=100A, V_{GS}=10V$	-	130	-	nC
Gate-Source Charge <sup>4</sup>	$Q_{gs}$		-	31.5	-	
Gate-Drain Charge <sup>4</sup>	$Q_{gd}$		-	10.5	-	
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>						
Diode Forward Voltage <sup>3</sup> ( $T_J=25^\circ\text{C}$ )	$V_{SD}$	$V_{GS}=0V, I_S=200A$	-	-	1.2	V
Diode Forward Current <sup>2</sup>	$I_S$	-	-	-	120	A
Reverse Recovery Time	$t_{rr}$	$I_r=I_S, di/dt=100A/\mu s^3, T_J=25^\circ\text{C}$	-	67	-	nS
Reverse Recovery Charge	$Q_{rr}$		-	112	-	nC

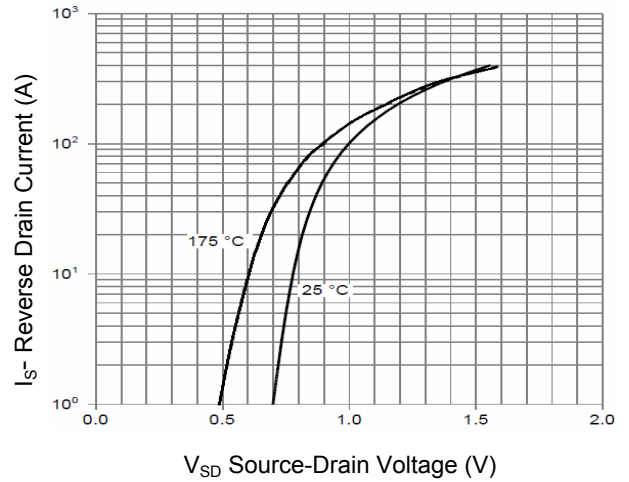
Note:

1. Repetitive rating: Pulsed width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board,  $t \leq 10$  sec.
3. Pulse test: pulse width  $\leq 300\mu s$ , duty cycle  $\leq 2\%$ .
4. Guaranteed by design, not subject to production
5.  $E_{AS}$  condition :  $T_J=25^\circ\text{C}, V_{DD}=30V, V_G=10V, L=0.5mH, R_G=25\Omega$

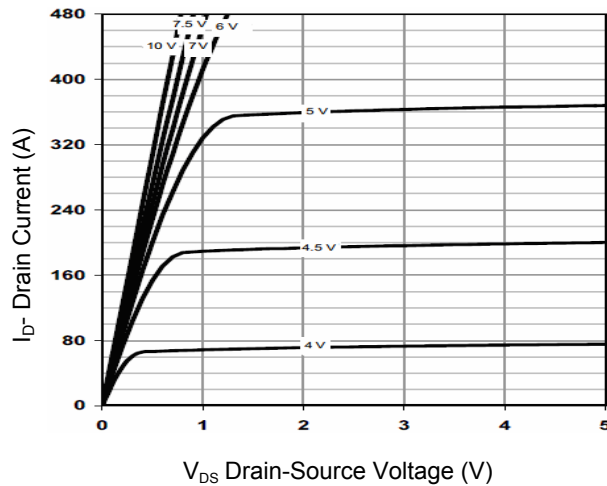
**Typical Electrical and Thermal Characteristic Curves**



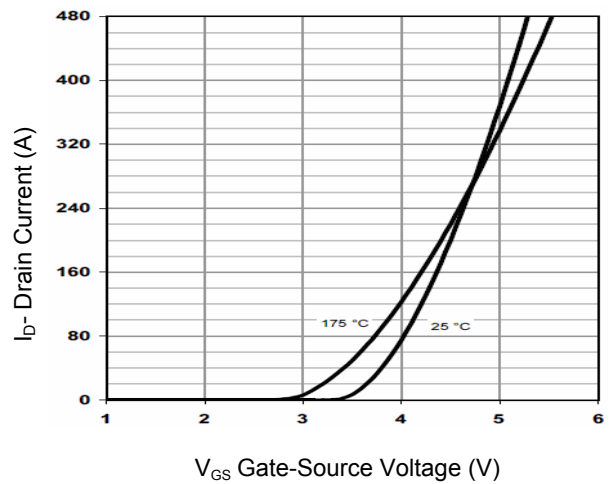
**Figure 1. Safe Operating Area**



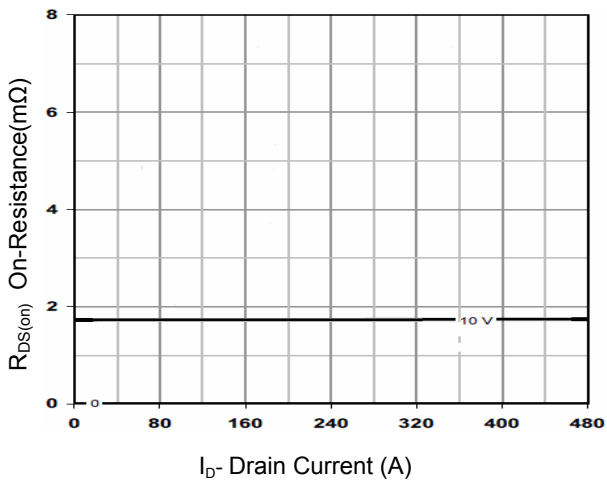
**Figure 2. Source-Drain Diode Forward Voltage**



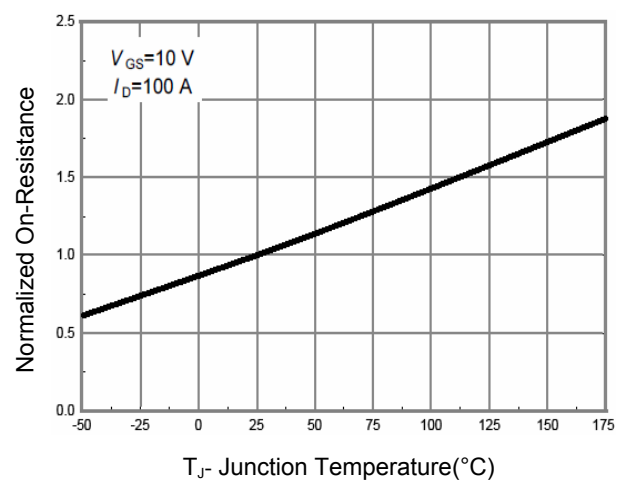
**Figure 3. Output Characteristics**



**Figure 4. Transfer Characteristics**

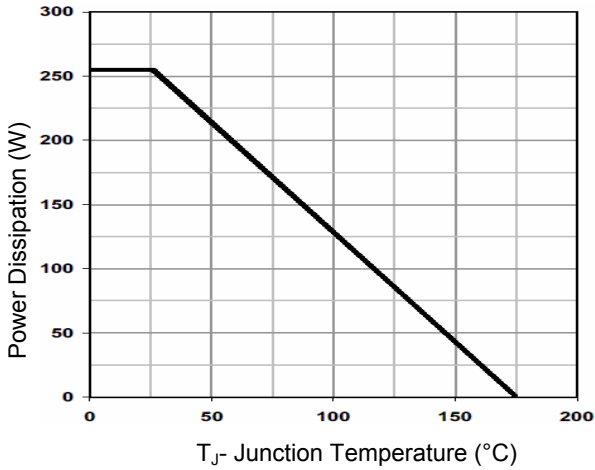


**Figure 5. Rdson-Drain Current**

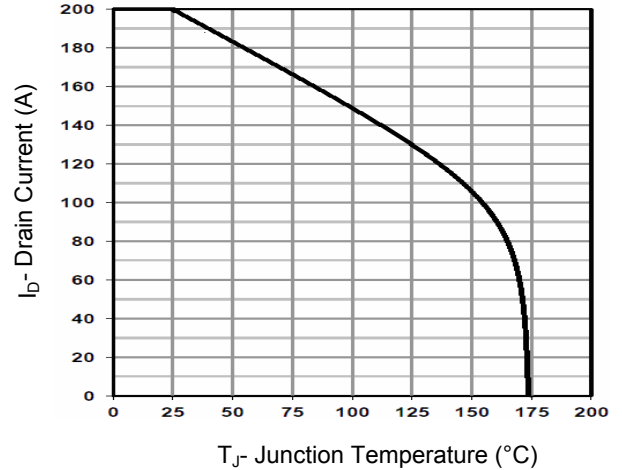


**Figure 6.  $R_{DS(ON)}$  vs. Junction Temperature**

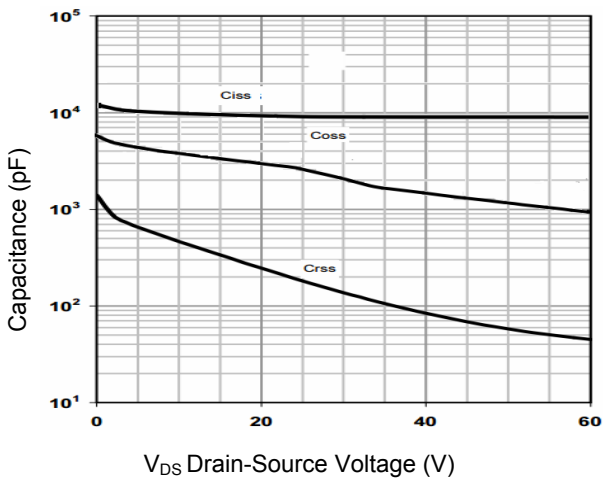
**Typical Electrical and Thermal Characteristic Curves**



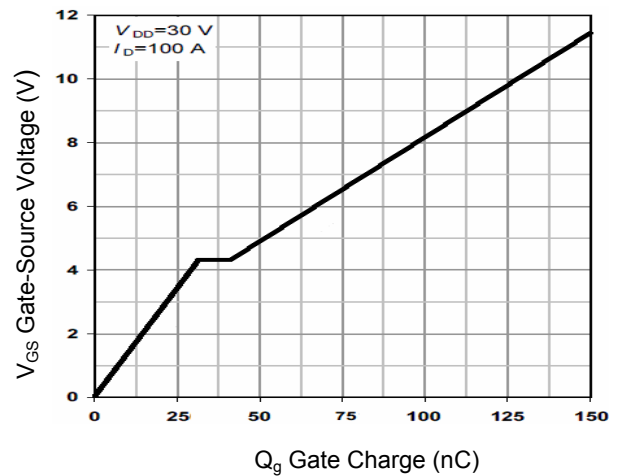
**Figure 7. Power De-rating**



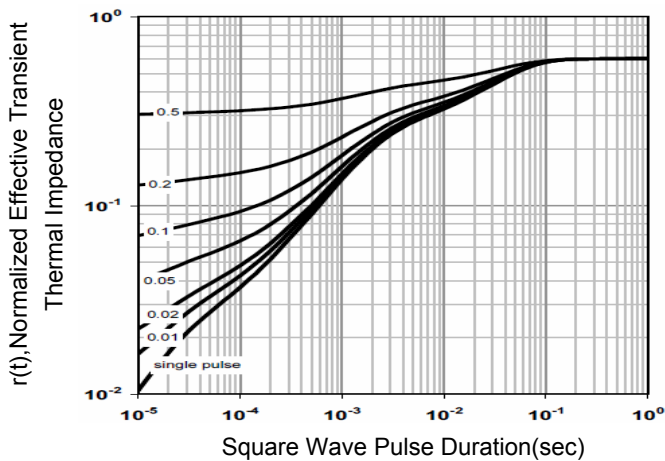
**Figure 8. Current De-rating**



**Figure 9. Capacitance**

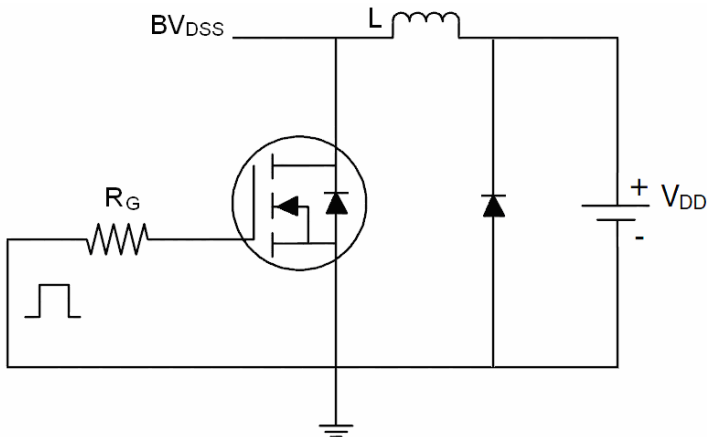


**Figure 10. Gate Charge Waveforms**

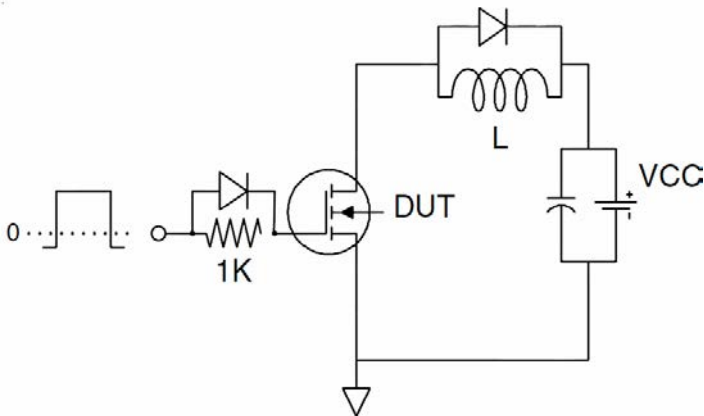


**Figure 11. Normalized Maximum Transient Thermal Impedance**

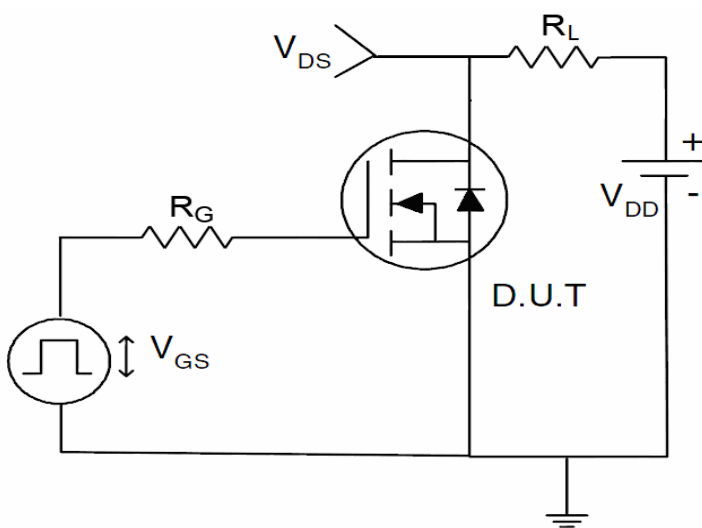
**Test Circuit**



**Figure 12. E<sub>AS</sub> Test Circuit**

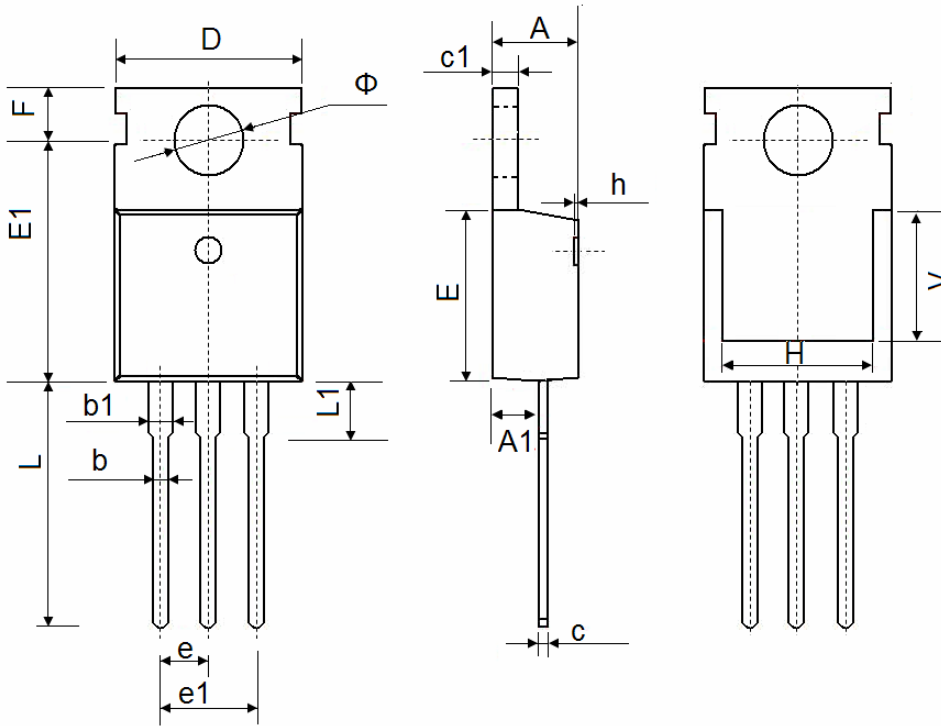


**Figure 13. Gate Charge Test Circuit**



**Figure 14. Switch Time Test Circuit**

**Package Outline Dimensions (TO-220)**



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	4.4	4.6	0.173	0.181
A1	2.25	2.55	0.089	0.1
b	0.71	0.91	0.028	0.036
b1	1.17	1.37	0.046	0.054
c	0.33	0.65	0.013	0.026
c1	1.2	1.4	0.047	0.055
D	9.91	10.25	0.39	0.404
E	8.95	9.75	0.352	0.384
E1	12.65	12.95	0.498	0.51
e	2.540 TYP.		0.100 TYP.	
e1	4.98	5.18	0.196	0.204
F	2.65	2.95	0.104	0.116
H	7.9	8.1	0.311	0.319
h	0	0.3	0	0.012
L	12.9	13.4	0.508	0.528
L1	2.85	3.25	0.112	0.128
V	7.500 REF.		0.295 REF.	
Φ	3.4	3.8	0.134	0.15